

# LNJ0F1C5FRA4

## Hight Bright Surface Mounting Chip LED

Strobe Type

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	103	mW
Forward current	$I_F$	25	mA
Pulse forward current *	$I_{FP}$	50	mA
Reverse current	$I_R$	100	mA
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

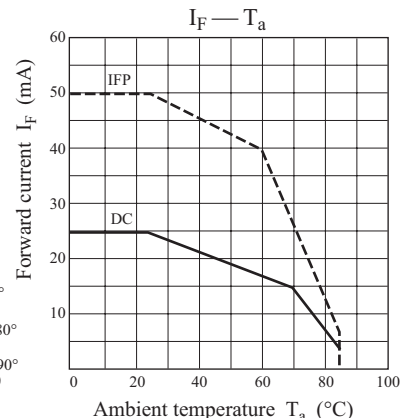
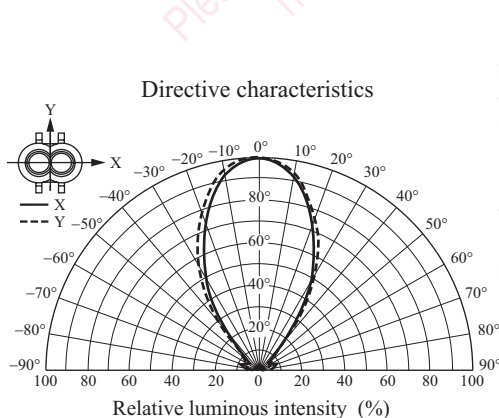
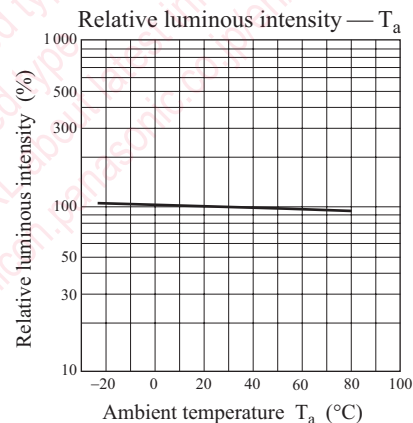
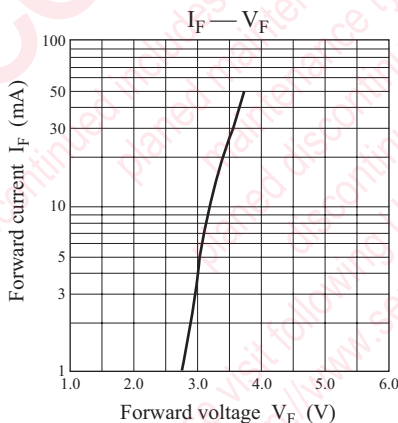
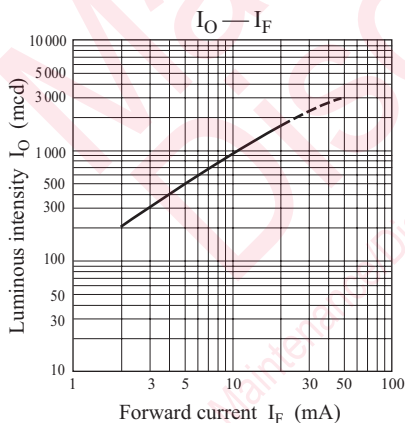
■ Lighting Color

- White

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

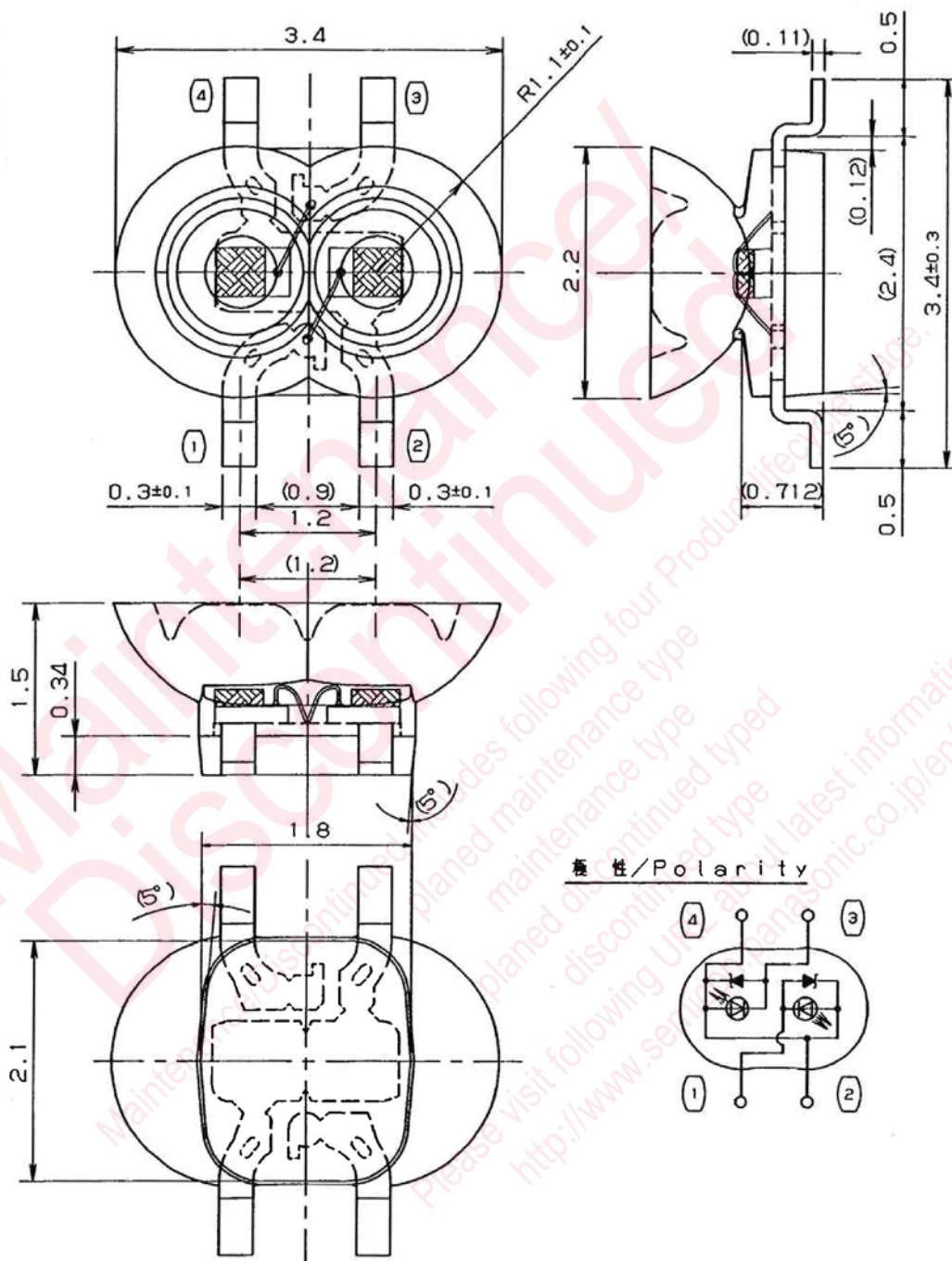
■ Electro-Optical Characteristics  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_{O-20}$	$I_F = 20 \text{ mA / chip}$	1350	1800		mcd
Forward voltage	$V_F$	$I_F = 20 \text{ mA / chip}$	3.0	3.4	4.0	V
Chromaticity coordinates	x	$I_F = 20 \text{ mA / chip}$	0.280		0.320	—
	y	$I_F = 20 \text{ mA / chip}$	0.260		0.383	—



■ Package (Unit: mm)

LLTLTN4GF100



- Pin name
- 1, 3: Cathode
- 2, 4: Anode

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